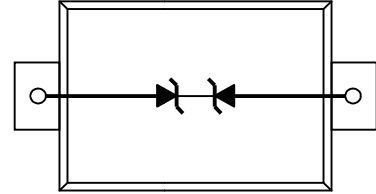


**Features**

- 130 Watts Peak Pulse Power per Line (tp = 8/20µs)
- Working voltages: 5V
- Low Leakage Current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology
- Provides ESD protection to IEC61000-4-2(ESD): ±25kV (air discharge), ±25kV (contact discharge)



**Applications**

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Pagers Peripherals

**Absolute Maximum Rating**

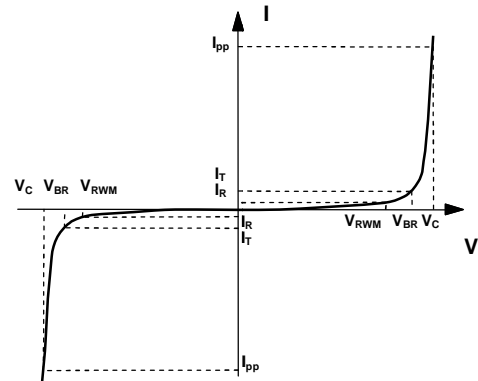
	Symbol	Value	Units
Peak Pulse Power (tp =8/20µs)	P <sub>PP</sub>	130	Watts
ESD Voltage (Contact)	V <sub>ESD</sub>	±25	kV
ESD Voltage (Air)	V <sub>ESD</sub>	±25	kV
Lead Soldering Temperature	T <sub>L</sub>	260 (10 sec.)	°C
Operating Temperature Range	T <sub>OP</sub>	-55 to 150	°C
Storage Temperature	T <sub>STG</sub>	-55 to 155	°C

**Electrical Characteristics (@ 25°C Unless Otherwise Specified)**

Type Number	Reverse Stand-Off Voltage	Minimum Breakdown Voltage	Peak Pulse Voltage @8/20µS	V <sub>c</sub> @8/20µS		Reverse Leakage @V <sub>RWM</sub>	Typical Capacitance
	V <sub>RWM</sub>	V <sub>BR</sub> @1mA	V <sub>c</sub> @5A	(max.)	@I <sub>PP</sub>	I <sub>R</sub> @V <sub>RWM</sub>	DC=0V C <sub>J</sub> @ 1 MHz
	V	V	V	V	A	µA	pF
RLSD52A051C	5.0	5.5	12.5	15	9	1.0	15

**Electrical Parameters (T=25°C)**

Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current



**Characteristic Curves**

Fig 1. 8/20µs Pulse Waveform

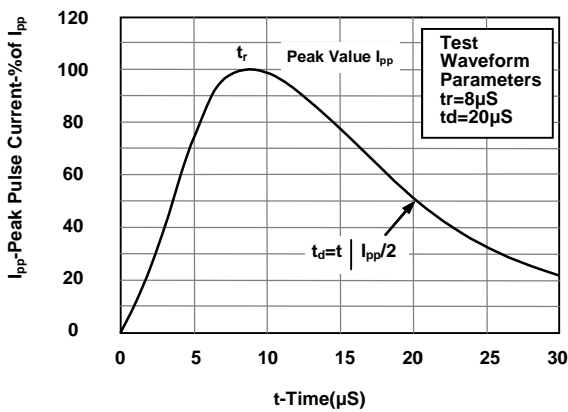


Fig 3. Power Derating Curve

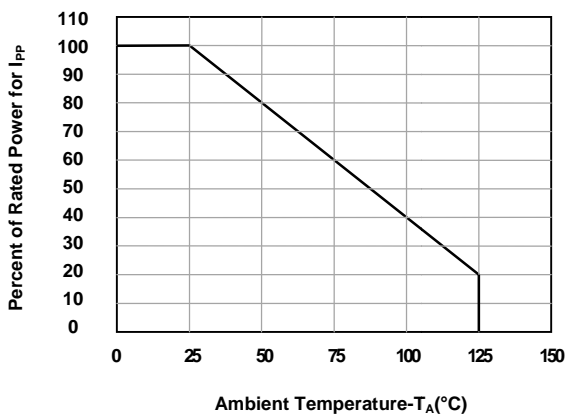


Fig2.ESD Pulse Waveform (according to IEC61000-4-2)

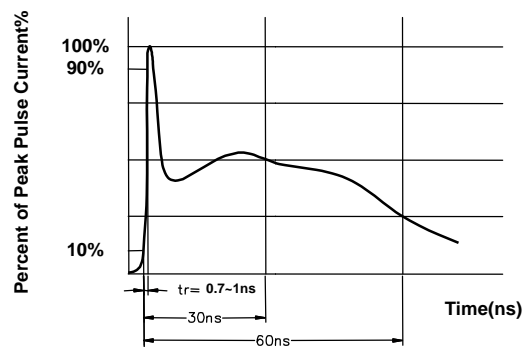
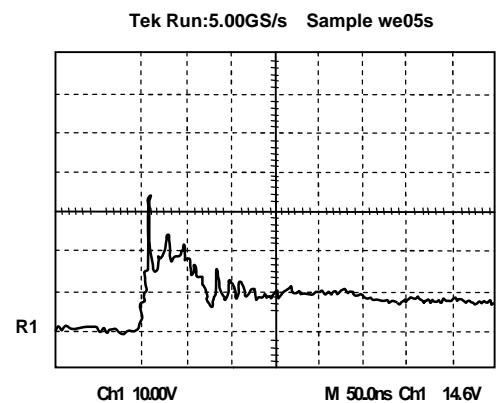
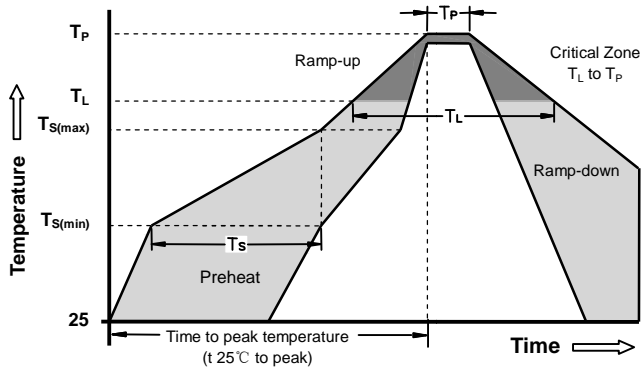


Figure 4.ESD Clamping(8KV Contact per IEC61000-4-2)



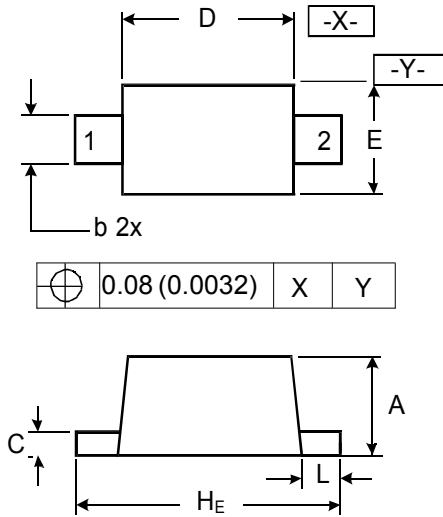
### Soldering Parameters - Reflow Soldering (Surface Mount Devices)




Reflow Condition		Pb - Free assembly
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	150°C
	-Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 -180 Seconds
Average ramp up rate ( Liquids Temp $T_L$ ) to peak		3°C/second max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	- Temperature ( $T_L$ ) (Liquids)	217°C
	- Time (min to max) ( $t_s$ )	60 -150 Seconds
Peak Temperature ( $T_P$ )		260 +0/-5°C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 - 40 Seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_P$ )		8 minutes Max
Do not exceed		280°C

Package outline dimensions

SOD-523



	0.08 (0.0032)	X	Y
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DIMENSIONS

SYMBOL	MILLIMETER		INCHES	
	MIN	MAX	MIN	MAX
A	0.50	0.70	0.020	0.028
b	0.25	0.35	0.010	0.014
C	0.07	0.20	0.0028	0.0079
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
H <sub>E</sub>	1.50	1.70	0.059	0.067
L	0.15	0.25	0.006	0.010

Marking



Ordering information

Order code	Package	Base qty	Delivery mode
UMW RLSD52A051C	SOD-523	3000	Tape and reel

单击下面可查看定价，库存，交付和生命周期等信息

[>>UMW\(友台半导体\)](#)